

Electronic Patent Application Fee Transmittal

Application Number:	10823221			
Filing Date:	13-Apr-2004			
Title of Invention:	METHODS OF FORMING INTEGRATED CIRCUITS DEVICES HAVING PAD CONTACT PLUGS IN THE CELL ARRAY AND PERIPHERAL CIRCUIT REGIONS OF THE INTEGRATED CIRCUIT SUBSTRATE			
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Attorney Docket Number:	5649-1228			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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